

ABSTRACT
WAFER PROCESSING METHOD

A wafer processing method includes a modified layer forming step of forming a modified layer along a planned dividing line within a wafer and a dividing step of dividing the wafer along the planned dividing line with the modified layer as a starting point by applying a force to the wafer. The modified layer forming step includes a forward path modified layer forming step, a backward path modified layer forming step, and a phase shift mask reversing step of reversing a phase shift mask so as to reverse phase distribution of a laser beam applied to the wafer in an X-axis direction after the forward path modified layer forming step and before the backward path modified layer forming step, or after the backward path modified layer forming step and before the forward path modified layer forming step.

(Figure 6A)